

B2887 Board Size (mm)



B2887 BOARD SPECIFICATIONS

- 1. Board Layers: 8
- 2. Layer Stack Order:
Layer1 (Artwork_1): Top Signal_2, 0.5 oz, diff. 100 ohms
Layer2 (Artwork_2): Power_1, P5V, 1 oz
Layer3 (Artwork_3): Power_2, Ground, 1 oz
Layer4 (Artwork_4): Bot Signal_2, 0.5 oz, diff 100 ohms
- 3. Apply silkscreen on both side:
Artwork_5: Top silkscreen.
Artwork_6: Bot silkscreen.
- 4. Apply solder mask over bare copper on both side:
Artwork_7: Top solder mask
Artwork_8: Bottom solde mask
- 5. Material: FR4
- 6. Board thickness: 0.062'' +/- 0.010.
- 7. TRACE IMPEDENCE: diff 100 ohms +/- 10% for all signal layers.
- 8. Emersion gold plating over bare copper
- 9. All layers mininum trace width/clearence/width = 5/5/5 mils,
- 10. Trace width can be adusted by matching the impedance requirement by manufacturing
- 11. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE (Inch)

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
○	.01	182	YES	---
⊞	.015	8	YES	---
⊘	.035	40	YES	---
⊞	.041	2	YES	---
⊖	.048	23	YES	---
⊞	.13779528	4	YES	---

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SCHM# B2886
SPEC# B2887
ASSM# B2888

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
B2887 Specification

SHEET 1 OF 1
DATE 02/01/2017
DRAWN TANG

B- 2887
REV 1.0